

Title (en)
TITANIUM PLATE

Title (de)
TITANPLATTE

Title (fr)
PLAQUE DE TITANE

Publication
EP 2397569 A4 20120725 (EN)

Application
EP 10741293 A 20100212

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Abstract (en)
[origin: EP2397569A1] An object of the present invention is to provide a titanium plate having high strength and excellent workability. In order to achieve the above object, there is provided a titanium plate having, by mass, an iron content of more than 0.10% and less than 0.60%, an oxygen content of more than 0.005% and less than 0.10%, a carbon content of less than 0.015%, a nitrogen content of less than 0.015%, a hydrogen content of less than 0.015%, with the balance being titanium and unavoidable impurities, wherein a two-phase structure of an α -phase and a β -phase is formed, and the β -phase is formed so as to have a circle-equivalent average grain size of 3 μm or less.

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Citation (search report)
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AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

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